

SiHL620S-VB Datasheet

Power MOSFET

PRODUCT SUMMARY

V_{DS} (V)	200	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.30
Q_g (Max.) (nC)	43	
Q_{gs} (nC)	7.0	
Q_{gd} (nC)	23	
Configuration	Single	

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



RoHS*
COMPLIANT
HALOGEN
FREE
Available

D²PAK (TO-263)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	200	V
Gate-Source Voltage			V_{GS}	± 20	
Continuous Drain Current	V_{GS} at 10 V	$T_C = 25\text{ }^\circ\text{C}$	I_D	10	A
		$T_C = 100\text{ }^\circ\text{C}$		6.7	
Pulsed Drain Current ^a			I_{DM}	36	
Linear Derating Factor				0.59	W/ $^\circ\text{C}$
Linear Derating Factor (PCB Mount) ^e				0.025	
Single Pulse Avalanche Energy ^b			E_{AS}	250	mJ
Repetitive Avalanche Current ^a			I_{AR}	9.0	A
Repetitive Avalanche Energy ^a			E_{AR}	7.4	mJ
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D		74	W
Maximum Power Dissipation (PCB Mount) ^e	$T_A = 25\text{ }^\circ\text{C}$			3.0	

* Pb containing terminations are not RoHS compliant, exemptions may apply

Peak Diode Recovery dV/dt^c	dV/dt	5.0	V/ns
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ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^{\circ}\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	

Notes

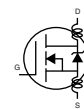
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. $V_{DD} = 50\text{ V}$, starting $T_J = 25\text{ }^{\circ}\text{C}$, $L = 4.6\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 9.0\text{ A}$ (see fig. 12).
 c. $I_{SD} \leq 9.0\text{ A}$, $dl/dt \leq 120\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^{\circ}\text{C}$.
 d. 1.6 mm from case.
 e. When mounted on 1" square PCB (FR-4 or G-10 material).

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	-	-	40	$^{\circ}\text{C}/\text{W}$
Maximum Junction-to-Ambient	R_{thJA}	-	-	62	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	-	1.7	

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		200	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.24	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V		-	-	25	μA
		V _{DS} = 160V, V _{GS} = 0 V, T _J = 125 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 5.4 A ^b	-	0.30	-	Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 5.4 A ^b		3.8	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	800	-	pF
Output Capacitance	C _{oss}			-	240	-	
Reverse Transfer Capacitance	C _{rss}			-	76	-	
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 5.9 A, V _{DS} = 160 V see fig. 6 and 13 ^b	-	-	43	nC
Gate-Source Charge	Q _{gs}			-	-	7.0	
Gate-Drain Charge	Q _{gd}			-	-	23	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 100 V, I _D = 5.9 A R _g = 12 Ω, R _D = 16 Ω see fig. 10 ^b		-	9.4	-	ns
Rise Time	t _r			-	28	-	
Turn-Off Delay Time	t _{d(off)}			-	39	-	
Fall Time	t _f			-	20	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	



SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	9.0	A
Pulsed Diode Forward Current ^a	I_{SM}		-	-	36	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_S = 9.0\text{ A}$, $V_{GS} = 0\text{ V}^b$	-	-	2.0	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_F = 5.9\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}^b$	-	170	340	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	1.1	2.2	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
 c. When mounted on 1" square PCB (FR-4 or G-10 material).

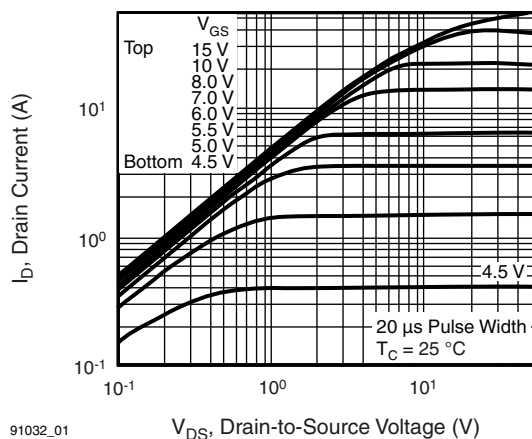
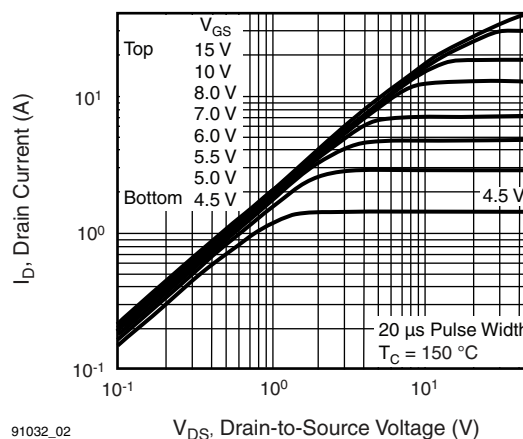
TYPICAL CHARACTERISTICS ($25\text{ }^{\circ}\text{C}$, unless otherwise noted)**Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^{\circ}\text{C}$** **Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ }^{\circ}\text{C}$**



Fig. 3 - Typical Transfer Characteristics

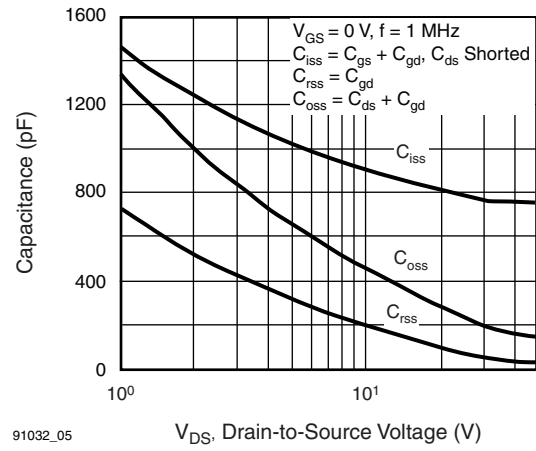


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

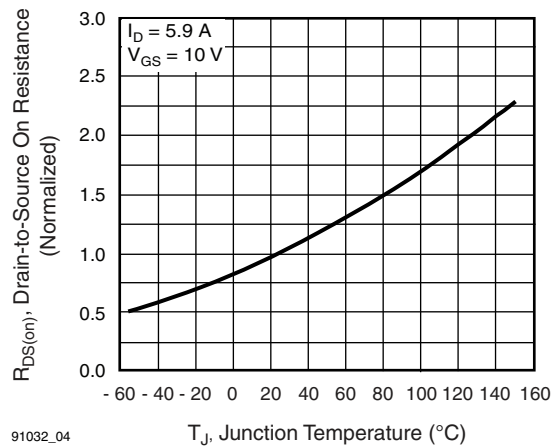
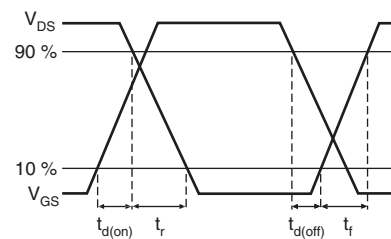
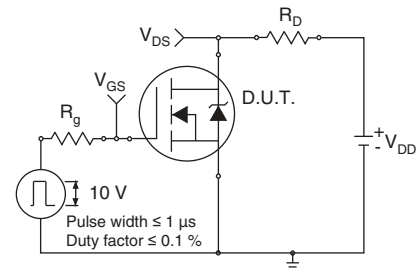
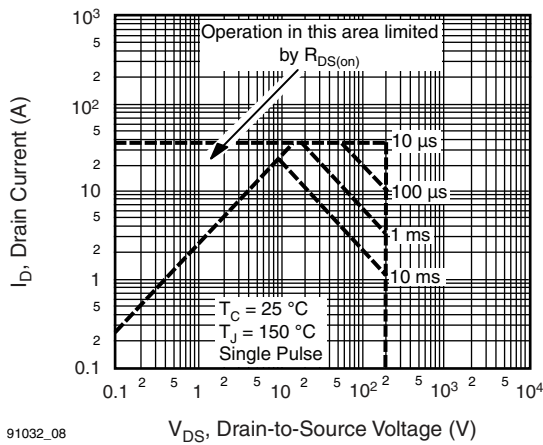
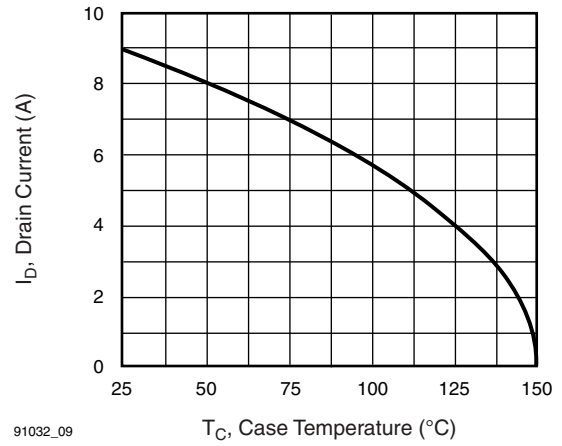
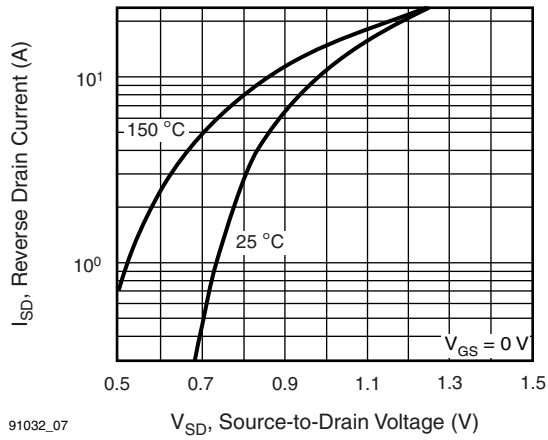


Fig. 4 - Normalized On-Resistance vs. Temperature



Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



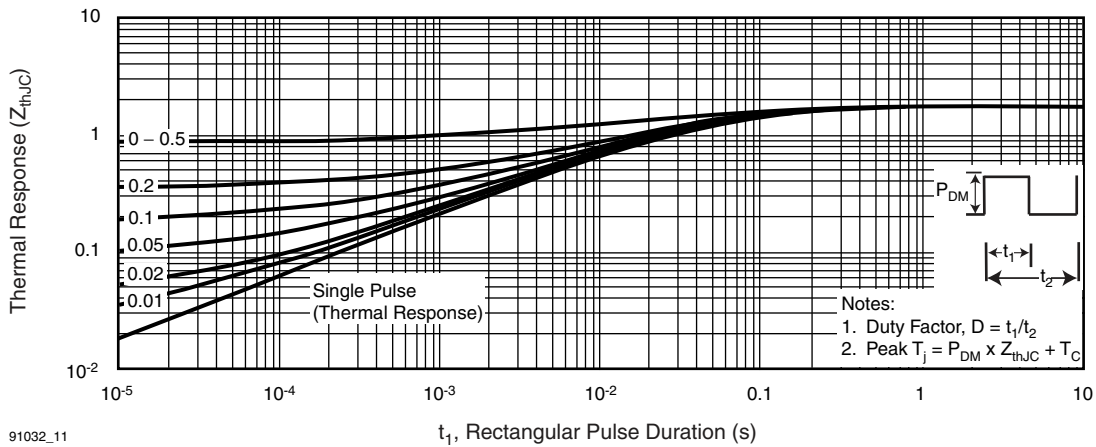


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

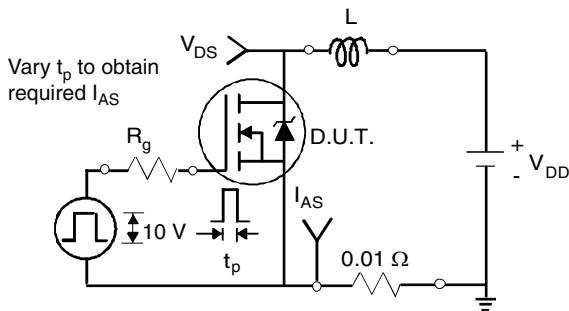


Fig. 12a - Unclamped Inductive Test Circuit

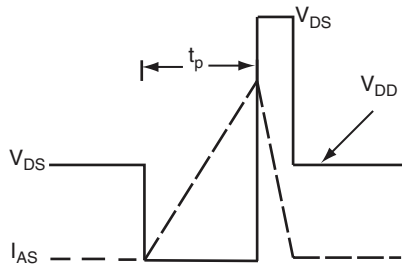


Fig. 12b - Unclamped Inductive Waveforms



Fig. 12c - Maximum Avalanche Energy vs. Drain Current

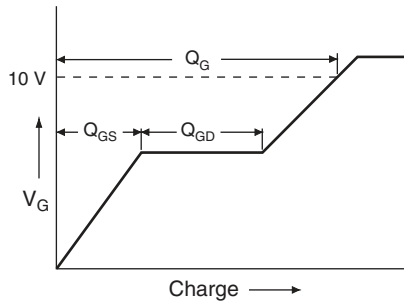


Fig. 13a - Basic Gate Charge Waveform

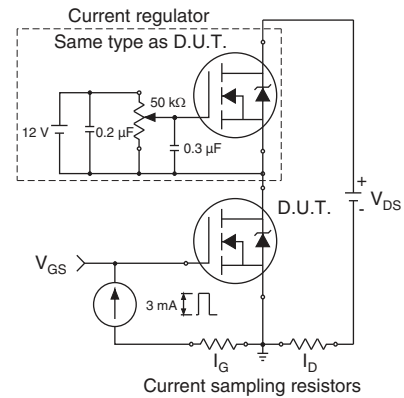


Fig. 13b - Gate Charge Test Circuit

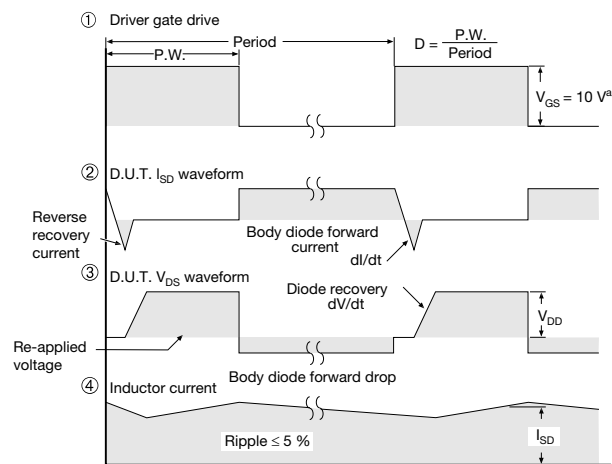
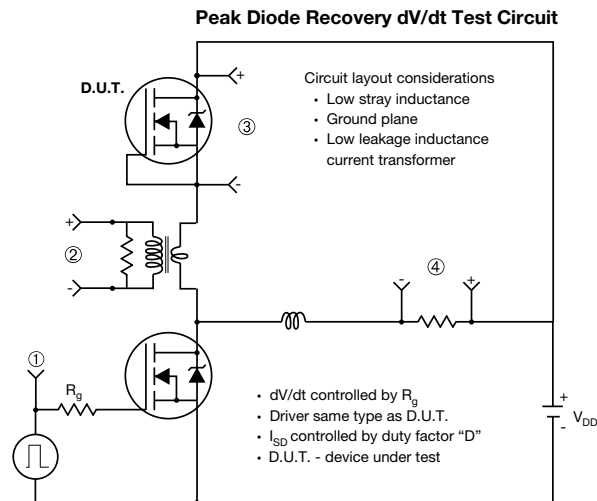
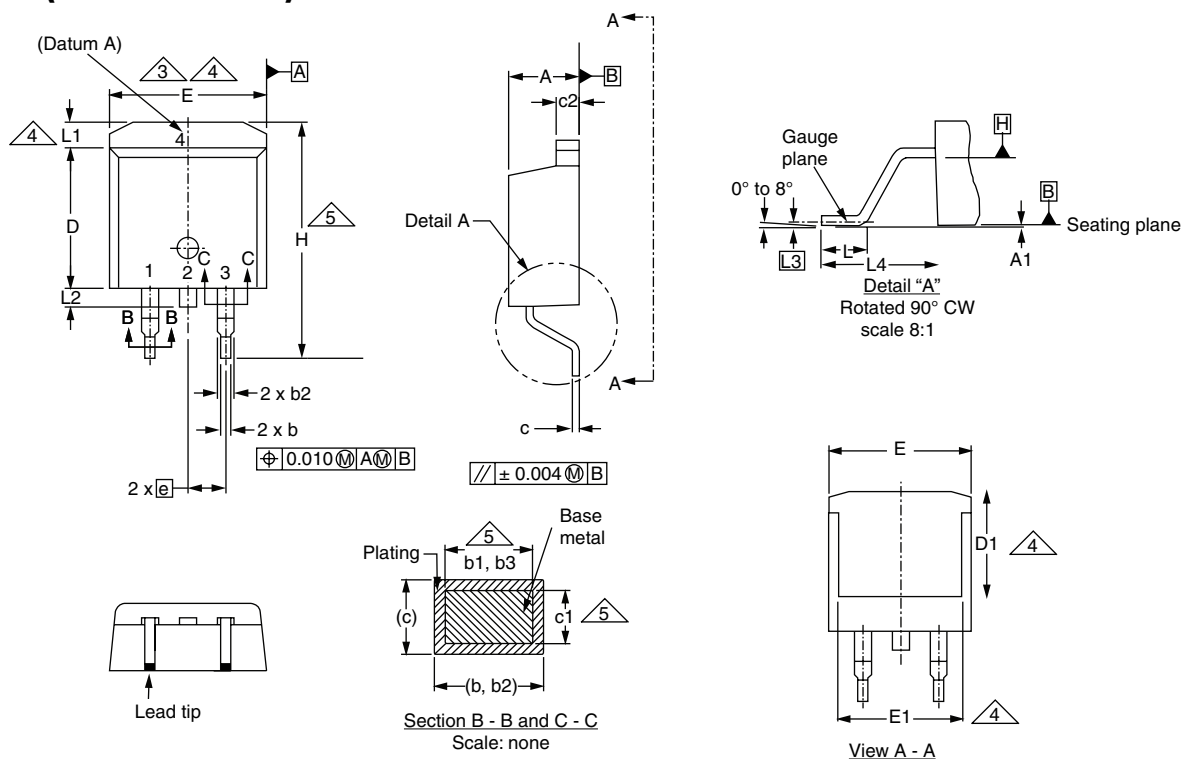
**Note**a. $V_{GS} = 5 \text{ V}$ for logic level devices

Fig. 14 - For N-Channel

TO-263AB (HIGH VOLTAGE)

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
 DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

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